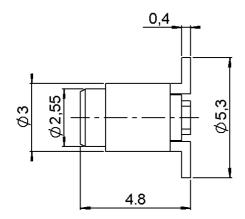
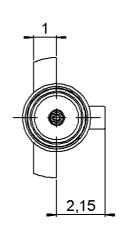
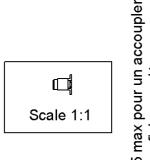
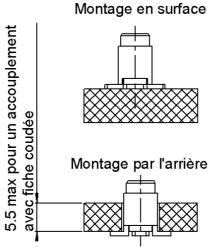
R199.005.523

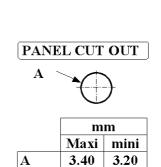
Series: MC-CARD





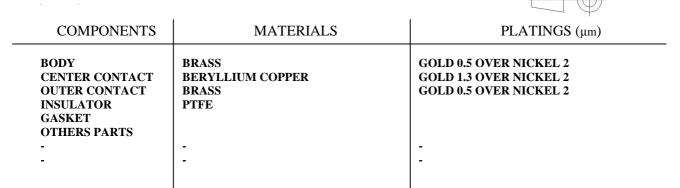






Uniquement pour montage arrière

All dimensions are in mm.



**Issue:** 0430 D



Series : MC-CARD

R199.005.523

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# **PACKAGING**

Standard	Unit	Other
1	-	Contact us

## **SPECIFICATION**

917 686 82

#### **ELECTRICAL CHARACTERISTICS**

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-8} \;\; \text{GHz} \end{array}$ 

VSWR 1.15 + 0.015 x F(GHz) Maxi

Insertion loss RF leakage - (  $\sqrt{F(GHz)}$  dB Maxi - F(GHz)) dB Maxi

Voltage rating 170 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 M $\Omega$  mini

## **ENVIRONMENTAL**

Operating temperature -65/+165 ° C Hermetic seal NA Atm.cm3/s

Panel leakage NA

## **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

# MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.153** g

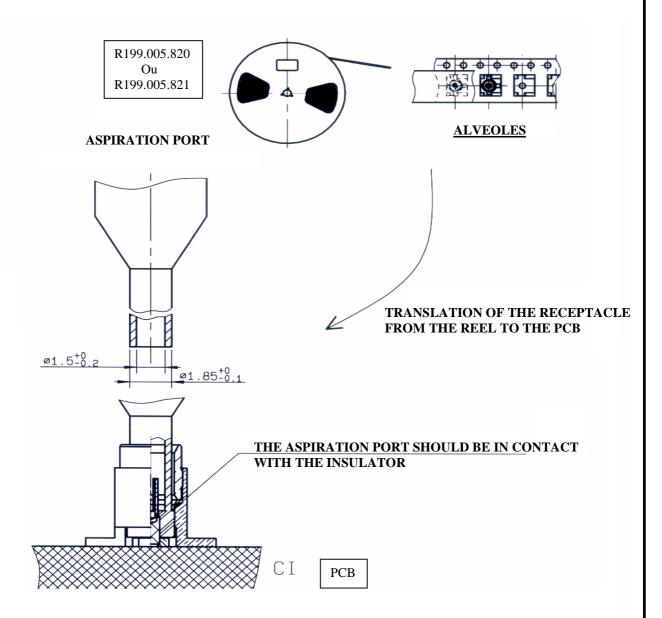
**Issue:** 0430 D



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Series: MC-CARD

# **MC-CARD SERIES - INFORMATIONS**



**Issue:** 0430 D

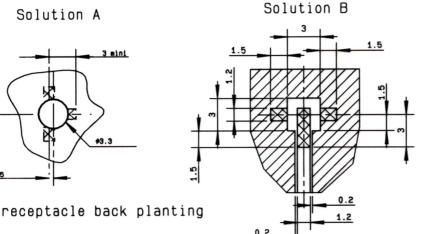


R199.005.523

Series: MC-CARD

# MC-CARD SERIES - INFORMATIONS

Solution A 0.3:0.05





Pattern

Land for solder paste

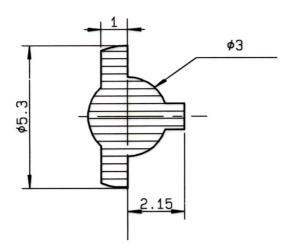
Same printed circuit that B + DIA 0.13

Solution A



COPLANAR LINE Pattern and signal are on the same side Thickness of PCB: .063 (1.6 mm)
The material of PCB is the epoxy r.cin of glass fabrics bacs.(Er = 4.8) The solder resist should be printed exept for the land nattern on the PCB.

# SHADOW OF MC-CARD RECEPTACLE FOR VIDEO CAMERA



**Issue:** 0430 D



R199.005.523

Series: MC-CARD

#### **SOLDER PROCEDURE**

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

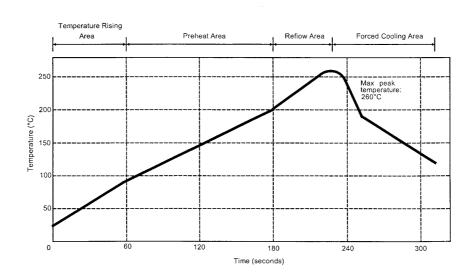
We advise a thickness of 200 microns. Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

## TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

**Issue:** 0430 D

